

# PMEG6010CEH; PMEG6010CEJ

1 A very low  $V_F$  MEGA Schottky barrier rectifiers

Rev. 02 — 27 March 2007

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifiers with an integrated guard ring for stress protection, encapsulated in small and flat lead Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package		Configuration
	NXP	JEITA	
PMEG6010CEH	SOD123F	-	single
PMEG6010CEJ	SOD323F	SC-90	single

### 1.2 Features

- Forward current:  $I_F \leq 1$  A
- Reverse voltage:  $V_R \leq 60$  V
- Very low forward voltage
- Small and flat lead SMD plastic packages

### 1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications

### 1.4 Quick reference data



Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_F$	forward current	$T_{sp} \leq 55$ °C	-	-	1	A
$V_R$	reverse voltage		-	-	60	V
$V_F$	forward voltage	$I_F = 1$ A	[1] -	570	660	mV

[1] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .

## 2. Pinning information

**Table 3. Pinning**

Pin	Description	Simplified outline	Symbol
1	cathode	 001aab540	 sym001
2	anode		

[1] The marking bar indicates the cathode.

## 3. Ordering information

**Table 4. Ordering information**

Type number	Package		
	Name	Description	Version
PMEG6010CEH	-	plastic surface-mounted package; 2 leads	SOD123F
PMEG6010CEJ	SC-90	plastic surface-mounted package; 2 leads	SOD323F

## 4. Marking

**Table 5. Marking codes**

Type number	Marking code
PMEG6010CEH	CA
PMEG6010CEJ	EQ

## 5. Limiting values

**Table 6. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit		
$V_R$	reverse voltage		-	60	V		
$I_F$	forward current	$T_{sp} \leq 55\text{ °C}$	-	1	A		
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms};$ $\delta \leq 0.25$	-	7	A		
$I_{FSM}$	non-repetitive peak forward current	square wave; $t_p = 8\text{ ms}$					
			PMEG6010CEH	-	9	A	
			PMEG6010CEJ	-	10	A	
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$					
			PMEG6010CEH	[1]	-	375	mW
				[2]	-	830	mW
			PMEG6010CEJ	[1]	-	350	mW
				[2]	-	830	mW
$T_j$	junction temperature		-	150	°C		
$T_{amb}$	ambient temperature		-65	+150	°C		
$T_{stg}$	storage temperature		-65	+150	°C		

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 6. Thermal characteristics

**Table 7. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit		
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]					
			PMEG6010CEH	[2]	-	-	330	K/W
				[3]	-	-	150	K/W
			PMEG6010CEJ	[2]	-	-	350	K/W
				[3]	-	-	150	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]					
			PMEG6010CEH	-	-	60	K/W	
			PMEG6010CEJ	-	-	55	K/W	

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

[4] Soldering point of cathode tab.

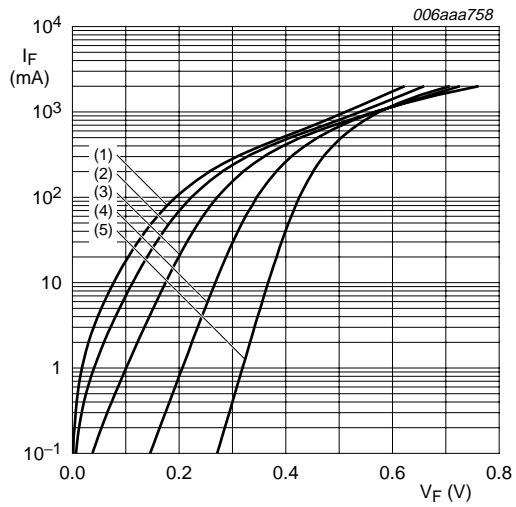
## 7. Characteristics

**Table 8. Characteristics**

$T_{amb} = 25^\circ\text{C}$  unless otherwise specified.

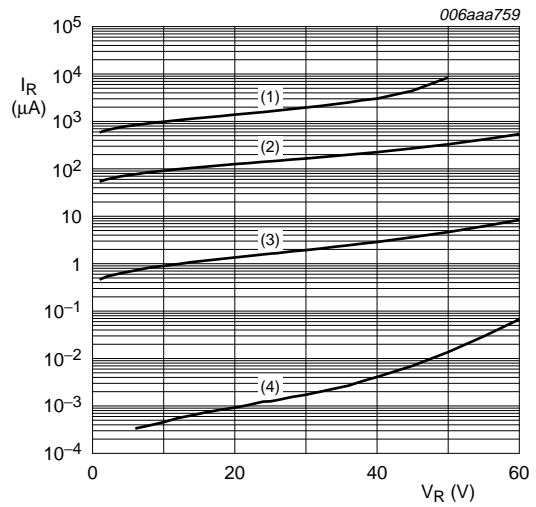
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage		[1]			
		$I_F = 1\text{ mA}$	-	210	250	mV
		$I_F = 10\text{ mA}$	-	270	310	mV
		$I_F = 100\text{ mA}$	-	350	400	mV
		$I_F = 500\text{ mA}$	-	460	530	mV
		$I_F = 700\text{ mA}$	-	510	580	mV
		$I_F = 1\text{ A}$	-	570	660	mV
$I_R$	reverse current	$V_R = 5\text{ V}$	-	0.8	-	$\mu\text{A}$
		$V_R = 10\text{ V}$	-	1.1	-	$\mu\text{A}$
		$V_R = 60\text{ V}$	-	11	50	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$	-	60	68	pF

[1] Pulse test:  $t_p \leq 300\ \mu\text{s}; \delta \leq 0.02$ .



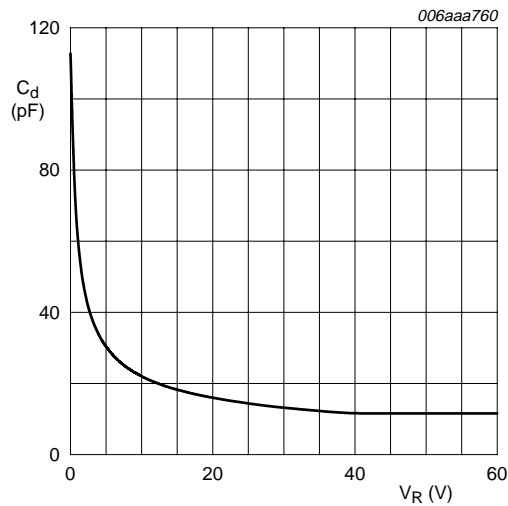
- (1)  $T_{amb} = 150\text{ °C}$
- (2)  $T_{amb} = 125\text{ °C}$
- (3)  $T_{amb} = 85\text{ °C}$
- (4)  $T_{amb} = 25\text{ °C}$
- (5)  $T_{amb} = -40\text{ °C}$

**Fig 1. Forward current as a function of forward voltage; typical values**



- (1)  $T_{amb} = 125\text{ °C}$
- (2)  $T_{amb} = 85\text{ °C}$
- (3)  $T_{amb} = 25\text{ °C}$
- (4)  $T_{amb} = -40\text{ °C}$

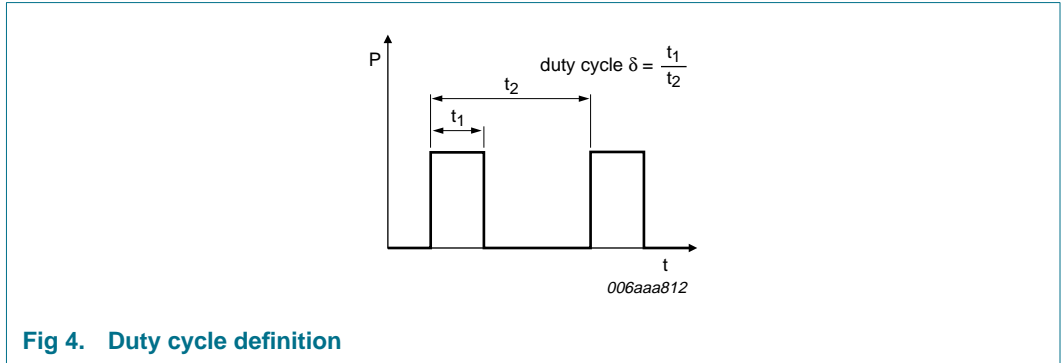
**Fig 2. Reverse current as a function of reverse voltage; typical values**



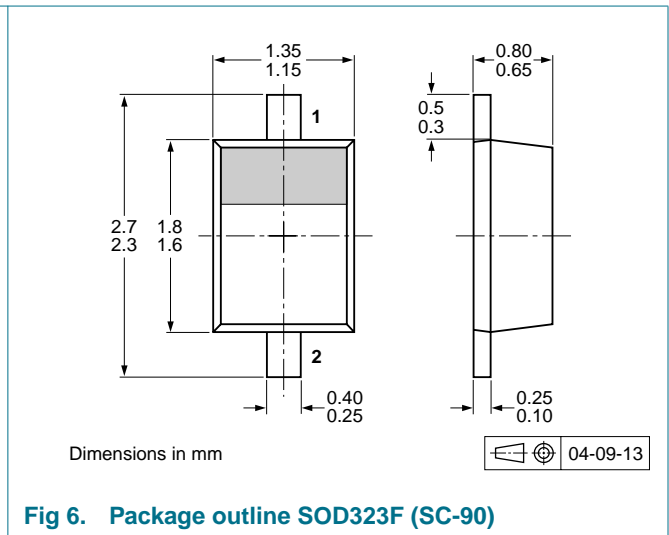
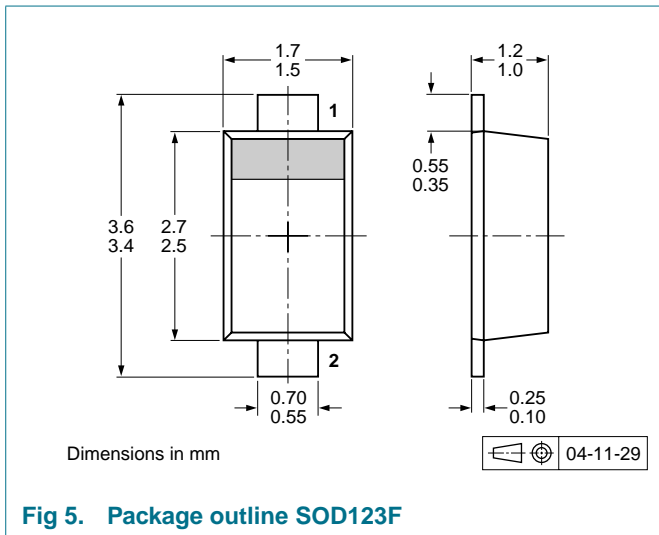
$f = 1\text{ MHz}; T_{amb} = 25\text{ °C}$

**Fig 3. Diode capacitance as a function of reverse voltage; typical values**

**8. Test information**



**9. Package outline**



**10. Packing information**

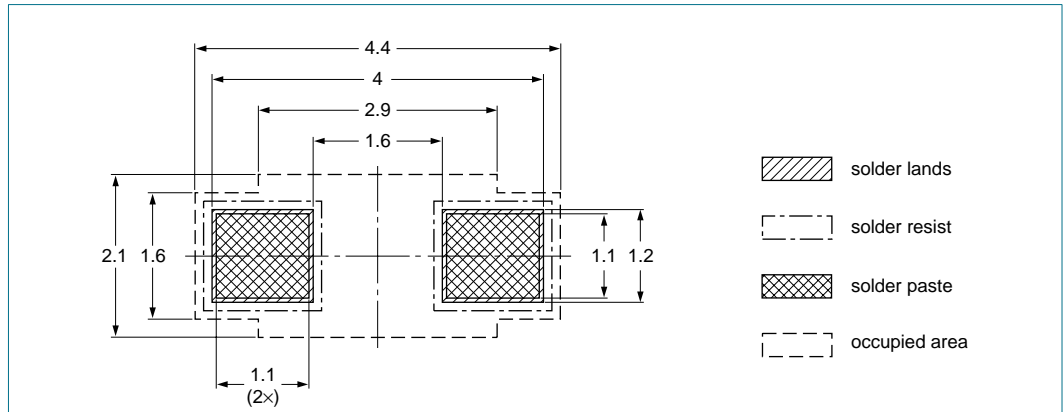
**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
PMEG6010CEH	SOD123F	4 mm pitch, 8 mm tape and reel	-115	-135
PMEG6010CEJ	SOD323F			

[1] For further information and the availability of packing methods, see [Section 14](#).

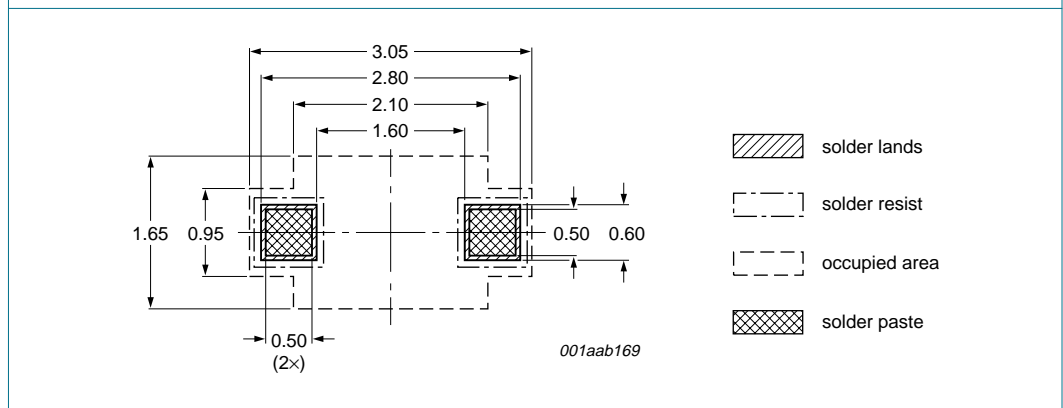
## 11. Soldering



Reflow soldering is the only recommended soldering method.

Dimensions in mm

**Fig 7. Reflow soldering footprint SOD123F**



Reflow soldering is the only recommended soldering method.

Dimensions in mm

**Fig 8. Reflow soldering footprint SOD323F (SC-90)**

## 12. Revision history

**Table 10. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG6010CEH_PMEG6010CEJ_2	20070327	Product data sheet	-	PMEG6010CEJ_1
Modifications:		<ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• Type number PMEG6010CEH added</li><li>• <a href="#">Section 1.1 "General description"</a>: amended</li><li>• <a href="#">Table 1 "Product overview"</a>: added</li><li>• <a href="#">Table 7 "Thermal characteristics"</a>: <a href="#">Table note 1</a> amended</li><li>• <a href="#">Section 8 "Test information"</a>: added</li></ul>		
PMEG6010CEJ_1	20060414	Product data sheet	-	-



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### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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